Erratum to Vol. 37, No. 3, March 2008

Ambient Temperature Ultrasonic Bonding of Si-Dice Using Sn-3.5wt.%Ag

JUNG-MO KIM,^{1,2} JAE-PIL JUNG,^{3,5} Y. NORMAN ZHOU,²
and JONG-HYEONG KIM⁴

1.—University of Seoul, Seoul, Republic of Korea. 2.—Department of Mech. Eng., University of Waterloo, Waterloo, Canada N2L 3G1. 3.—Department of Mater. Sci. and Eng., University of Seoul, Seoul 130-743, Republic of Korea. 4.—Seoul Nat'l University of Technology, Seoul 139-743, Republic of Korea. 5.—e-mail: jujung@uos.ac.kr

**Erratum to Journal of ELECTRONIC MATERIALS
DOI 10.1007/s11664-007-0341-z**

In this article, the last author's name was written incorrectly. The correct author's name is Jong-Hyeong Kim.